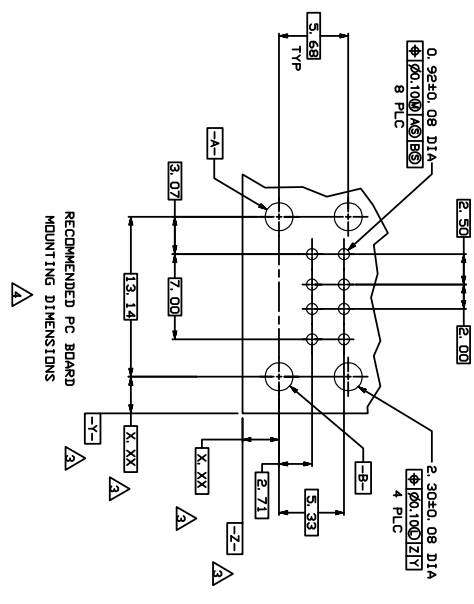
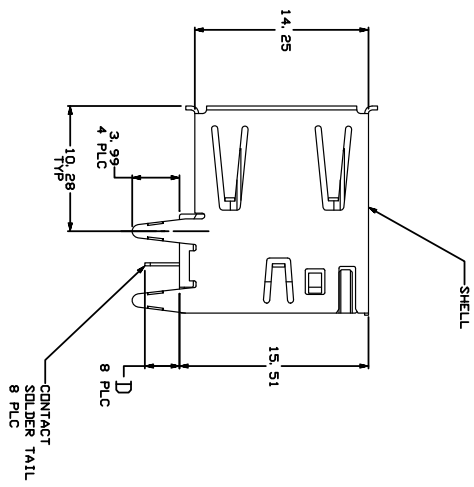
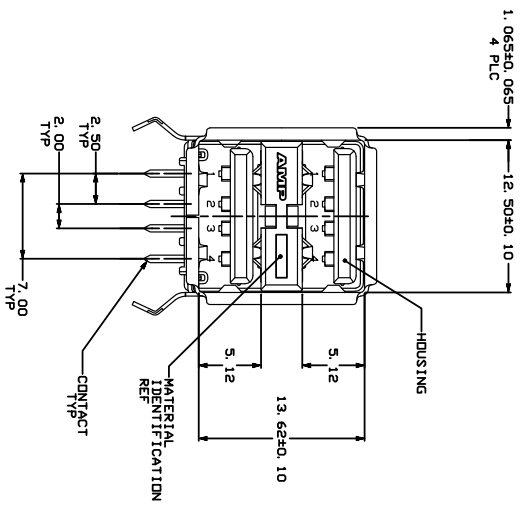


△ MATERIAL:
 SHELL & CONTACTS- COPPER ALLOY.
 HOUSING- UL 94V-0 RATED, THERMOPLASTIC, SEE TABLE.
 △ PLATING:
 CONTACTS- 0.075µm MINIMUM GOLD OVER 0.75µm MINIMUM
 PALLADIUM-NICKEL ON MATING AREA, OR CONTACT ALTERNATE
 PLATING 0.75µm MINIMUM GOLD ON MATING AREA,
 3.80µm MINIMUM WHITE TIN ON SOLDER TAILS,
 BOTH OVER 1.27µm MINIMUM NICKEL.
 SHELL- 2-5µm MINIMUM BRIGHT TIN
 △ BATH AND BASIC DIMENSIONS ESTABLISHED BY CUSTOMER.
 △ RECOMMENDED PCB BOARD THICKNESS OF 1.57.
 △ PLATING:
 CONTACTS- 0.127µm MINIMUM GOLD ON MATING AREA,
 3.80µm MINIMUM WHITE TIN ON SOLDER TAILS,
 ALL OVER 1.27µm MINIMUM NICKEL ON ENTIRE CONTACT.
 SHELL 2-5µm MINIMUM BRIGHT TIN
 △ PACKAGED IN TRAYS



RECOMMENDED PCB BOARD MOUNTING DIMENSIONS
 △

COMPATIBILITY	PLATING	HIGH TEMPERATURE COMPATIBLE	HOUSING COLOR	PART NUMBER
△	△	△	△	△
△	△	△	△	△
△	△	△	△	△
△	△	△	△	△
△	△	△	△	△
△	△	△	△	△
△	△	△	△	△
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△	△	△	△	△
△	△	△	△	△
△	△	△	△	△

THIS DRAWING IS A CONTROLLED DOCUMENT.

CONNECTIONS	ASSEMBLY METHOD	TEMPERATURE	YOUNG'S MODULUS	TENSILE STRENGTH
3 PL	REF. TO 3010	250°C	115,000 N/CM ²	275 N/CM ²
4 PL	REF. TO 3010	250°C	115,000 N/CM ²	275 N/CM ²
8 PLC	REF. TO 3010	250°C	115,000 N/CM ²	275 N/CM ²

RECEIPT ASSEMBLY, RIGHT ANGLE.
 SOLDERED THROUGH-HOLE, USB
 THIS DRAWING IS THE ORIGINAL
 CUSTOMER DRAWING